

ON Semiconductor®

BS270

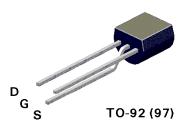
N-Channel Enhancement Mode Field Effect Transistor

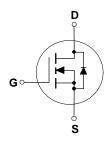
General Description

These N-Channel enhancement mode field effect transistors are produced using ON Semiconductor's proprietary, high cell density, DMOS technology. These products have been designed to minimize on-state resistance while provide rugged, reliable, and fast switching performance. They can be used in most applications requiring up to 500mA DC. These products are particularly suited for low voltage, low current applications such as small servo motor control, power MOSFET gate drivers, and other switching applications.

Features

- $\blacksquare \quad \text{400mA, 60V. } \mathsf{R}_{\mathsf{DS}(\mathsf{ON})} = 2\Omega \, \, @ \, \, \mathsf{V}_{\mathsf{GS}} = \mathsf{10V}.$
- High density cell design for low R_{DS(ON)}.
- Voltage controlled small signal switch.
- Rugged and reliable.
- High saturation current capability.





Absolute Maximum Ratings T_A = 25°C unless otherwise noted

Symbol	Parameter	BS270	Units
V _{DSS}	Drain-Source Voltage	60	V
V_{DGR}	Drain-Gate Voltage ($R_{os} \le 1M\Omega$)	60	V
V _{GSS}	Gate-Source Voltage - Continuous	<u>±20</u>	V
	- Non Repetitive (tp < 50µs)	±40	
I _D	Drain Current - Continuous	400	mA
	- Pulsed	2000	
P _D	Maximum Power Dissipation	625	mW
	Derate Above 25°C	5	mW/°C
T_J , T_{STG}	Operating and Storage Temperature Range	-55 to 150	°C
TL	Maximum Lead Temperature for Soldering Purposes, 1/16" from Case for 10 Seconds	300	°C
THERMA	L CHARACTERISTICS		
R _{eJA}	Thermal Resistacne, Junction-to-Ambient	200	°C/W

Symbol	Parameter	Conditions		Min	Тур	Max	Units
OFF CHAI	RACTERISTICS						
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{gs} = 0 \text{ V}, I_{D} = 10 \mu\text{A}$		60			V
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}$				1	μA
			$T_J = 125^{\circ}C$			500	μA
GSSF	Gate - Body Leakage, Forward	$V_{GS} = 20 \text{ V}, V_{DS} = 0 \text{ V}$				10	nA
GSSF	Gate - Body Leakage, Reverse	$V_{gs} = -20 \text{ V}, V_{DS} = 0 \text{ V}$				-10	nA
ON CHAR	ACTERISTICS (Note 1)						
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$		1	2.1	2.5	V
R _{DS(ON)}	Static Drain-Source On-Resistance	$V_{gs} = 10 \text{ V}, I_{D} = 500 \text{ mA}$			1.2	2	Ω
			T _J = 125°C		2	3.5	
		$V_{gs} = 4.5 \text{ V}, I_{D} = 75 \text{ mA}$			1.8	3	
V _{DS(ON)}	Drain-Source On-Voltage	$V_{GS} = 10 \text{ V}, I_{D} = 500 \text{ mA}$			0.6	1	V
		$V_{GS} = 4.5 \text{ V}, I_{D} = 75 \text{ mA}$			0.14	0.225	
I _{D(ON)}	On-State Drain Current	$V_{GS} = 10 \text{ V}, \ V_{DS} \ge 2 V_{DS(on)}$		2000	2700		mA
		$V_{GS} = 4.5 \text{ V}, \ V_{DS} \ge 2 V_{DS(on)}$		400	600		
g _{FS}	Forward Transconductance	$V_{DS} \ge 2 V_{DS(on)}$, $I_D = 200 \text{ mA}$		100	320		mS
DYNAMIC	CHARACTERISTICS						
C _{iss}	Input Capacitance	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$ $f = 1.0 \text{ MHz}$			20	50	pF
C _{oss}	Output Capacitance				11	25	pF
C _{rss}	Reverse Transfer Capacitance				4	5	pF
SWITCHIN	G CHARACTERISTICS (Note 1)						
t _{on}	Turn-On Time	$V_{DD} = 30 \text{ V}, I_{D} = 500 \text{ m A},$				10	ns
t _{off}	Turn-Off Time	$V_{GS} = 10 \text{ V}, R_{GEN} = 25 \Omega$				10	ns
DRAIN-SO	URCE DIODE CHARACTERISTICS AND	MAXIMUM RATINGS					
s	Maximum Continuous Drain-Source Diode Forward Current				400	mA	
SM	Maximum Pulsed Drain-Source Diode Fe	orward Current				2000	mA
V_{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S = 400 mA (Note 1)			0.88	1.2	V

Note: 1. Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2.0%.

Typical Electrical Characteristics

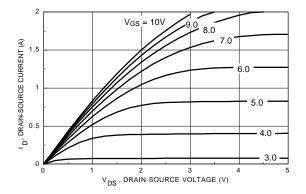


Figure 1. On-Region Characteristics.

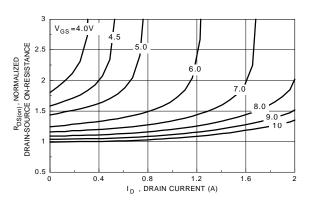


Figure 2. On-Resistance Variation with Gate Voltage and Drain Current.

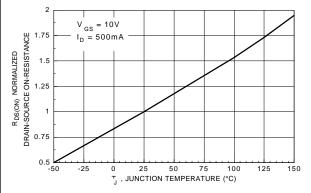


Figure 3. On-Resistance Variation with Temperature.

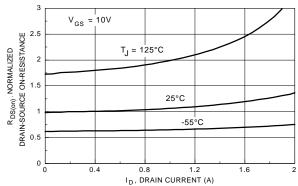


Figure 4. On-Resistance Variation with Drain Current and Temperature.

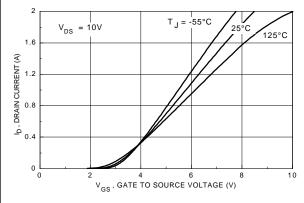


Figure 5. Transfer Characteristics.

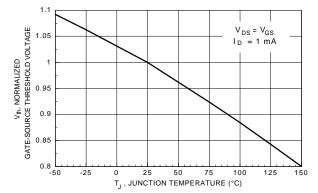


Figure 6. Gate Threshold Variation with Temperature.

Typical Electrical Characteristics (continued)

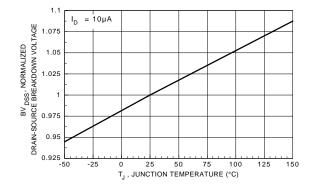


Figure 7. Breakdown Voltage Variation with Temperature.

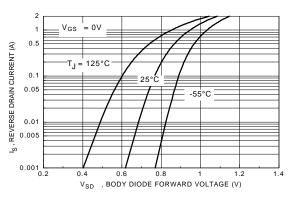


Figure 8. Body Diode Forward Voltage Variation with Current and Temperature.

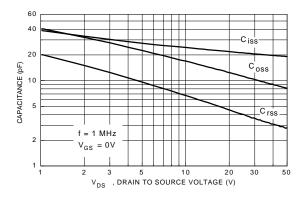


Figure 9. Capacitance Characteristics.

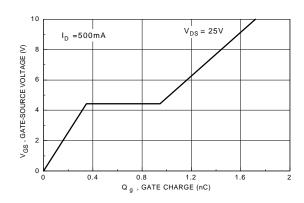


Figure 10. Gate Charge Characteristics.

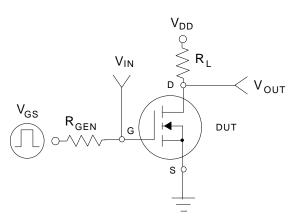


Figure 11. Switching Test Circuit.

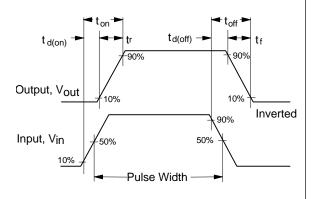


Figure 12. Switching Waveforms.

Typical Electrical Characteristics (continued)

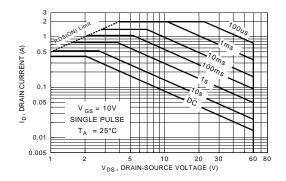


Figure 13. Maximum Safe Operating Area.

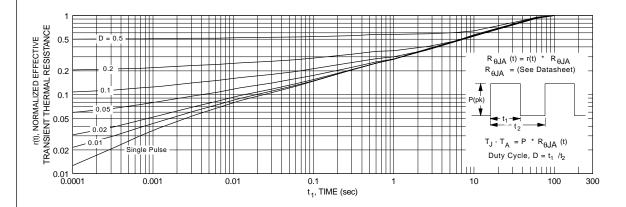
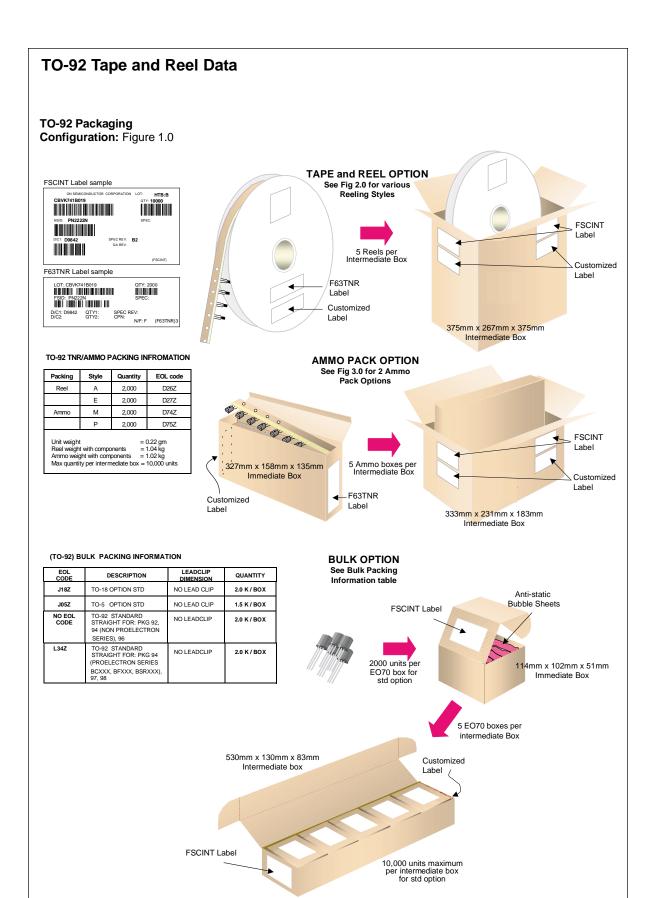


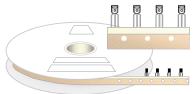
Figure 14. Transient Thermal Response Curve.



TO-92 Tape and Reel Data, continued

TO-92 Reeling Style Configuration: Figure 2.0

Machine Option "A" (H)

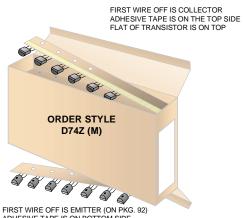


Style "A", D26Z, D70Z (s/h)

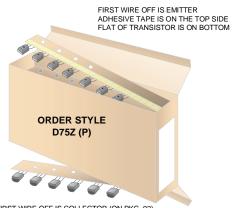
Machine Option "E" (J)

Style "E", D27Z, D71Z (s/h)

TO-92 Radial Ammo Packaging Configuration: Figure 3.0



FIRST WIRE OFF IS EMITTER (ON PKG. 92 ADHESIVE TAPE IS ON BOTTOM SIDE FLAT OF TRANSISTOR IS ON BOTTOM

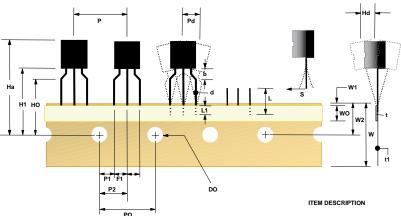


FIRST WIRE OFF IS COLLECTOR (ON PKG. 92) ADHESIVE TAPE IS ON BOTTOM SIDE FLAT OF TRANSISTOR IS ON TOP

TO-92 Tape and Reel Data, continued

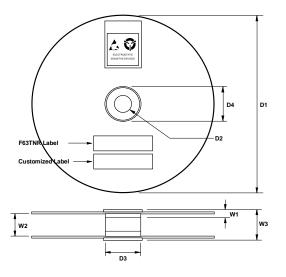
TO-92 Tape and Reel Taping

Dimension Configuration: Figure 4.0



User Direction of Feed

TO-92 Reel Configuration: Figure 5.0



ITEM DESCRIPTION	SYMBOL	DIMENSION
Base of Package to Lead Bend	b	0.098 (max)
Component Height	На	0.928 (+/- 0.025)
Lead Clinch Height	НО	0.630 (+/- 0.020)
Component Base Height	H1	0.748 (+/- 0.020)
Component Alignment (side/side)	Pd	0.040 (max)
Component Alignment (front/back)	Hd	0.031 (max)
Component Pitch	P	0.500 (+/- 0.020)
Feed Hole Pitch	PO	0.500 (+/- 0.008)
Hole Center to First Lead	P1	0.150 (+0.009, -0.010)
Hole Center to Component Center	P2	0.247 (+/- 0.007)
Lead Spread	F1/F2	0.104 (+/- 0 .010)
Lead Thickness	d	0.018 (+0.002, -0.003)
Cut Lead Length	L	0.429 (max)
Taped Lead Length	L1	0.209 (+0.051, -0.052)
Taped Lead Thickness	t	0.032 (+/- 0.006)
Carrier Tape Thickness	t1	0.021 (+/- 0.006)
Carrier Tape Width	W	0.708 (+0.020, -0.019)
Hold - down Tape Width	WO	0.236 (+/- 0.012)
Hold - down Tape position	W1	0.035 (max)
Feed Hole Position	W2	0.360 (+/- 0.025)
Sprocket Hole Diameter	DO	0.157 (+0.008, -0.007)
Lead Spring Out	S	0.004 (max)

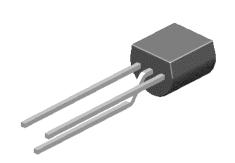
Note : All dimensions are in inches.

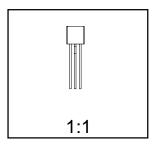
ITEM DESCRIPTION	SYSMBOL	MINIMUM	MAXIMUM
Reel Diameter	D1	13.975	14.025
Arbor Hole Diameter (Standard)	D2	1.160	1.200
(Small Hole)	D2	0.650	0.700
Core Diameter	D3	3.100	3.300
Hub Recess Inner Diameter	D4	2.700	3.100
Hub Recess Depth	W1	0.370	0.570
Flange to Flange Inner Width	W2	1.630	1.690
Hub to Hub Center Width	W3		2.090

Note: All dimensions are inches

TO-92 Package Dimensions

TO-92; TO-18 Reverse Lead Form (J35Z Option) (FS PKG Code 92, 94, 96)

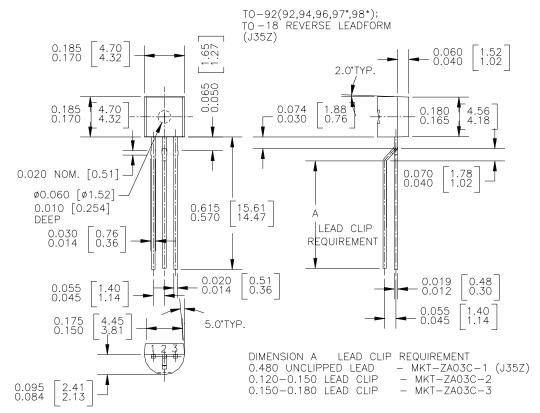




Scale 1:1 on letter size paper

Dimensions shown below are in: inches [millimeters]

Part Weight per unit (gram): 0.22



Note: All package 97 or 98 transistors are leadformed to this configuration prior to bulk shipment. Order L34Z option if in-line leads are preferred on package 97 or 98.

^{*} Standard Option on 97 & 98 package code

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